

RH-GEL500YBP

导热凝胶 Thermal Gel

Features and Benefits

特点与优势

- ✳ High thermal conductivity: 5.0W/m-K
导热系数: 5.0W/M-K
- ✳ It is widely used in sensitive electronic components
广泛应用于敏感电子元件
- ✳ Easy to operate. It can be painted by hand or dispensing equipment
便于操作.可通过手工方式或点胶设备来进行涂装



RH-GEL500YBP It is a soft two-component silicone based thermal gap filler with high thermal conductivity, low interfacial thermal resistance and good thixotropy. It is filled between the electronic components to be cooled and the radiator / shell, so as to make them contact closely, reduce the thermal resistance, quickly and effectively reduce the temperature of electronic components, so as to prolong the service life of electronic components and improve their reliability. After curing, it is elastomer, which can protect components.

RH-GEL500YBP 是一种柔软的双组份硅树脂基导热缝隙填充材料,具有高导热率、低界面热阻及良好的触变性。它填充于需冷却的电子元件与散热器/壳体等之间,使其紧密接触、减小热阻,快速有效地降低电子元件的温度,从而延长电子元件的使用寿命并提高其可靠性。固化后为弹性体,可以保护元器件。

The above suggestions and data are based on information that we believe to be reliable. Therefore, these suggestions and data are only for reference, not as product guarantee. It is up to the customer to decide whether the product is suitable or suitable for special use. We recommend that users first determine the suitability of our materials and recommendations before using them in large quantities.

以上建议及数据均来自我们认为可靠的资料。因此这些建议及数据仅供参考,而不作为产品保证。应由客户决定产品是否合适或适用特殊用途。我们建议用户在大量使用前,首先确定我们的材料适用性和建议。

RH-GEL500YBP			
Property	Parameter	Unit	Test Method
Color 颜色	粉红 Pinky	A 组分	Visual
	粉红 Pinky	B 组分	
Mixing ratio 混合比例	1:1	A:B	--
Density 密度	3.2	g/cm3	氦气真密度法
Thermal Conductivity 导热系数	5.0	W/m.k	ASTM D5470
Volume Resistivity 体积电阻率	>10 ¹³	Ωcm	ASTM D257
Dielectric Brekdown Voltage 击穿电压	>200	VAC/mil	ASTM D149
Permittivity 介电常数	5.0	@1M Hz	ASTM D150
Minimum Bonding Thickness 最小结合厚度	0.09	mm	--
Thermal expansion coefficient 热膨胀系数	175	ppm/K	ASTM E 831
硅小分子析出 D3~12 含量	<300	PPM	GB/T
D3~12 content of silicon small molecule precipitation			27843-2011
Working Temperature 工作温度	-50~200	℃	--
Fire Rating 防火等级	V-0	--	UL94
@25℃ Surface dry time@25℃ 表干时间	20	min	--
Full curing time 完全固化时间	4	25℃(H)	--
	10	100℃(min)	--
Hardness after curing 固化后硬度	50-90	Shore 00	ASTD D 2240
RoHS/REACH Compliance		--	--

使用 ASTM D5470 测试夹具,记录值包括界面热阻,数值仅供参考。实际应用性能到所施加的表面粗糙度、平整度和压力。注:厚度公差:±10%,硬度公差:±5°,颜色/厚度/硬度均可按顾客需求调试。

Applications 典型应用

- ✳ Suitable for high performance CPU / GPU 适用于高性能 CPU/GPU
- ✳ Hard disk, mobile phone, laptop 硬盘、手机、笔记本电脑
- ✳ Mobile and communication equipment 移动及通讯设备
- ✳ Automobile engine control equipment 汽车发动机控制设备
- ✳ Medical electronics, optical precision equipment 医疗电子,光学精密设备

Storage & Transportation: Store in a well ventilated, cool and dry place. Do not touch open fire. Store at 15-25 °C. This product is non-toxic and is stored and transported as non dangerous goods.

储存&运输: 贮存于通风、阴凉、干燥处,不要接触明火,贮存温度(15-25度)。本产品无毒,按非危险品贮存及运输。

Packaging: Syringe: 50CC/400CC 包装: 针管装: 50CC/400CC

Safety: please refer to material safety performance data (MSDS) of our company 安全: 请参阅本公司《材料安全性能数据 (MSDS)》

Period of validity: the product is valid for 12 months 有效期: 本产品有效期为 12 个月